



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



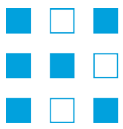
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48 Activated Rosin Cored Wire for Lead-Free and Lead Alloys

Product Description

Kester 48 Activated Rosin Flux for cored solder wire was developed for lead-free applications to enable soldering of most common metals. 48 has performance characteristics far exceeding standard RA fluxes. 48 builds on the performance of its predecessor Kester 44 with “instant-action” wetting to provide fast and reliable solder joints.

Performance Characteristics:

- Unparalleled wetting performance
- Excellent solderability and fast wetting to a variety of surface finishes
- Eliminates the need and expense of cleaning
- Low spattering
- Low smoke and odor
- Classified as ROM1 per J-STD-004

RoHS Compliance

Kester does not determine any applicable Restriction of Hazardous Substances (RoHS) exemptions for our lead containing products at the user level. (Applies only if this core flux is combined with a lead-free alloy)

Reliability Properties

Copper Mirror Corrosion: Low
Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Silver Chromate: Fail
Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Fluorides by Spot Test: Pass
Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

Surface Insulation Resistance (SIR), (typical): Pass
Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

Corrosion Test: Low
Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Chloride and Bromides: 1.05%
Tested to J-STD-004, IPC-TM-650, Method 2.3.35

	Blank	48
Day 1	1.6*10 ¹⁰ Ω	1.1*10 ¹⁰ Ω
Day 4	1.2*10 ¹⁰ Ω	9.2*10 ⁹ Ω
Day 7	1.1*10 ¹⁰ Ω	8.6*10 ⁹ Ω

Spread Test (typical):
Tested to J-STD-004, IPC-TM-650, Method 2.4.46

	Area of Spread mm ² (in ²)	
Flux Core Solder	Sn96.5Ag3.0Cu0.5	Sn63Pb37
285 Mildly Activated Rosin	213 (0.33)	335 (0.52)
275 No-Clean	219 (0.34)	361 (0.56)
44 Activated Rosin	220 (0.34)	342 (0.53)
48 Activated Rosin	245 (0.38)	419 (0.65)

Availability

48 flux cored wire is available in a wide variety of alloys, wire diameters and flux percentages and roll sizes. The most common alloys are Sn96.5Ag3.0Cu0.5 and K100LD. Please refer to www.kester.com for wire diameters, flux percentages and roll sizes that are available.

Note: Core Size 50, 58 and 66 = 1.1, 2.2 and 3.3% flux core

Process Considerations

Solder iron tip temperatures are most commonly between 371-400°C (700-750°F) for lead-free alloys. Heat both the land area and component lead to be soldered with the iron prior to apply the solder wire to the land area or component lead. Do not apply the wire directly to the soldering iron tip. This will shorten the life of the solder tip. If needed, Kester 186 flux may be used as a compatible liquid flux to aid in reworking soldered joints.

Cleaning

48 possesses excellent fluxing ability, the flux residue is non-corrosive and non-conductive under normal conditions of use. When exposed to an elevated temperature and humidity environment (38°C, 94% RH) for 72 hours, there is no evidence of corrosion caused by the flux residue. IPA will not clean the residues off the surface of the circuit board after the soldering process. A saponifier or cleaning agent specifically designed to clean a rosin based flux is required to clean the residues. Please contact Kester Technical Support for further information.

Storage and Shelf Life

Storage must be in a dry, non-corrosive environment. The surface may lose its shine and appear a dull shade of gray. This is a surface phenomena and is not detrimental to product functionality. Flux cored solder wire has a limited shelf life determined by the alloy used in the wire. For alloys containing more than 70% lead, the shelf life is two years from the date of manufacture. Other alloys have a shelf life of three years from the date of manufacture.

Health and Safety

This product, during handling or use, may be hazardous to your health or the environment. Read the Safety Data Sheet (SDS) and warning label before using this product.